

■ **FEATURES**

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

■ **TYPICAL APPLICATIONS**

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer and telecommunication.

■ **MECHANICAL DATA**

- **Package:** DO-214AC (SMA)
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

■ **MAXIMUM RATINGS** ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	M1G	M2G	M3G	M4G	M5G	M6G	M7G
Device marking code			M1	M2	M3	M4	M5	M6	M7
Maximum Repetitive Peak Reverse Voltage	VRRM	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	VRMS	V	35	70	140	280	420	560	700
Maximum DC blocking Voltage	VDC	V	50	100	200	400	600	800	1000
Average rectified output current @60Hz sine wave, Resistance load, TL (FIG.1)	I_O	A	1.0						
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, $T_j=25^\circ\text{C}$	I_{FSM}	A	30						
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, $T_j=25^\circ\text{C}$			60						
Current squared time @1ms≤t≤8.3ms $T_j=25^\circ\text{C}$, Rating of per diode	I^2t	A ² s	3.7						
Typical junction capacitance @Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	C_j	pF	6						
Storage temperature	T_{stg}	°C	-55 ~ +150						
Junction temperature	T_j	°C	-55 ~ +150						

■ **ELECTRICAL CHARACTERISTICS** ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	M1G	M2G	M3G	M4G	M5G	M6G	M7G
Maximum instantaneous forward voltage drop per diode	V_F	V	IFM=1.0A	1.1						
Maximum DC reverse current at rated DC blocking voltage per diode	I_R	μA	$T_j=25^\circ\text{C}$	5						
			$T_j=125^\circ\text{C}$	100						

■ **THERMAL CHARACTERISTICS** ($T_a=25^{\circ}\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	M1G	M2G	M3G	M4G	M5G	M6G	M7G
Typical Thermal Resistance	$R_{\theta J-A(1)}$	$^{\circ}\text{C/W}$	75						
	$R_{\theta J-L(1)}$	$^{\circ}\text{C/W}$	25						
	$R_{\theta J-C(1)}$	$^{\circ}\text{C/W}$	20						

Note

- (1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

■ **CHARACTERISTICS (TYPICAL)**

FIG.1: I_o - T_L Curve

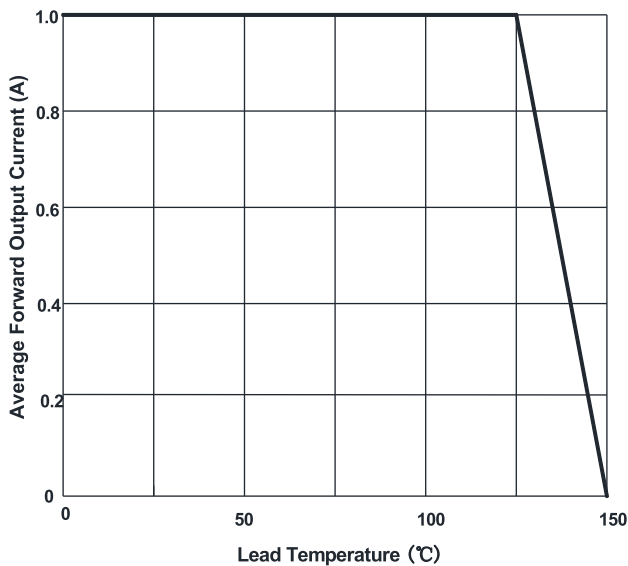


FIG.2: Forward Surge Current Capability

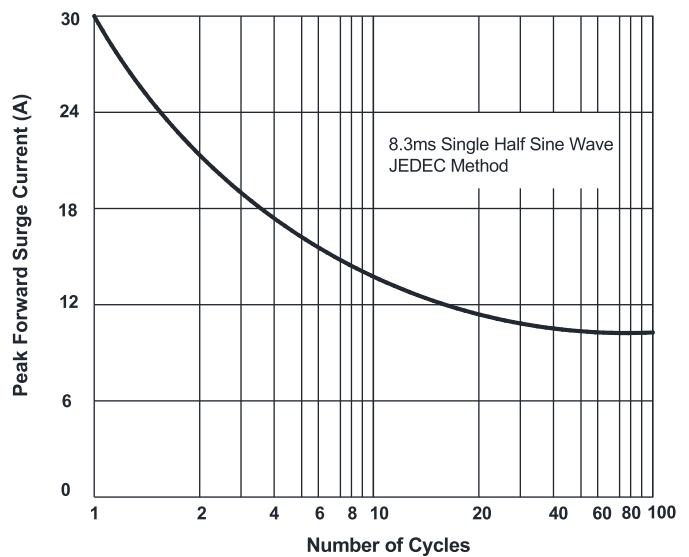


FIG.3: Typical Forward Voltage

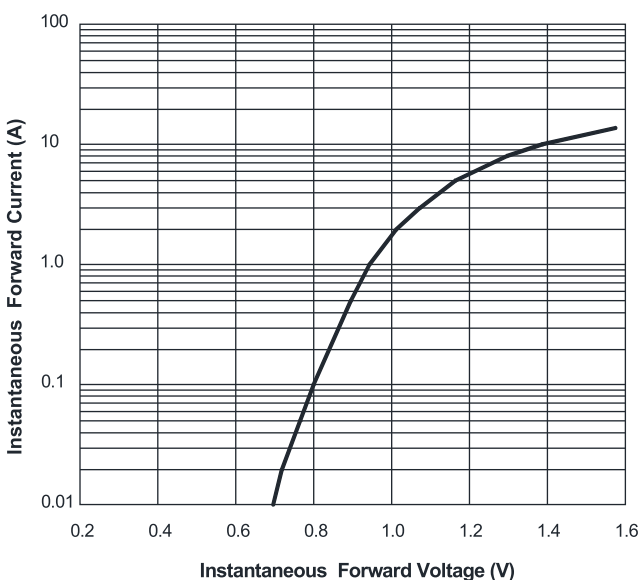
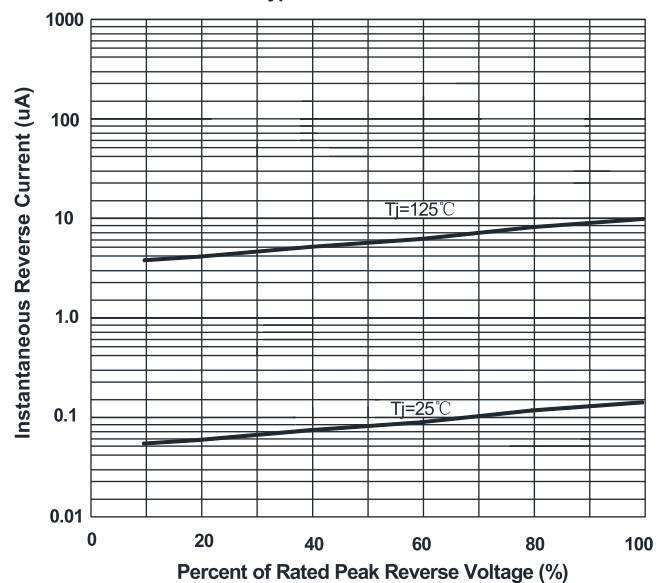
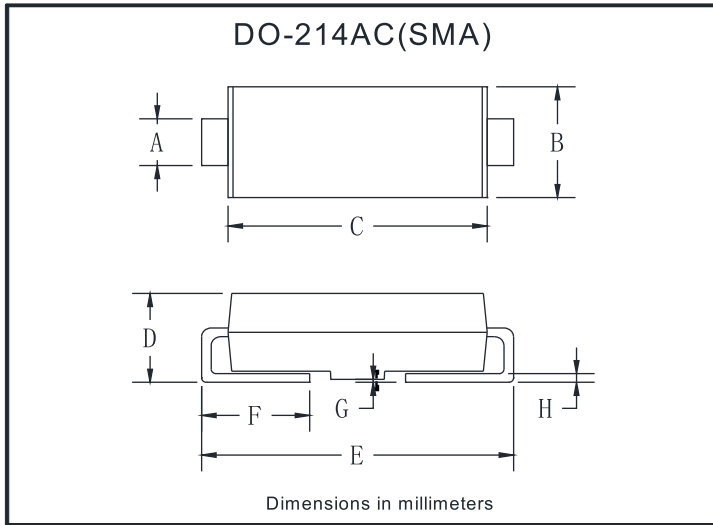


FIG.4: Typical Reverse Characteristics

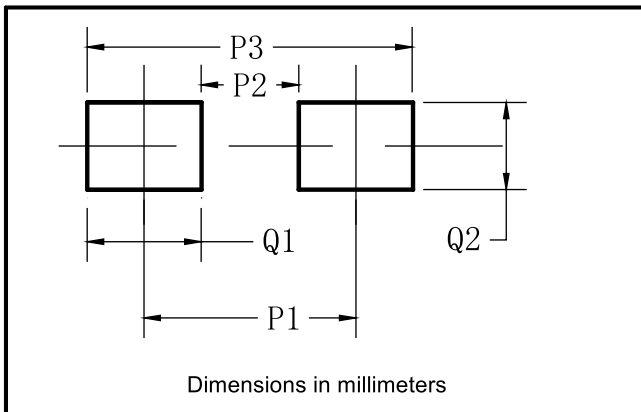


■ **OUTLINE DIMENSIONS**



DO-214AC(SMA)		
Dim	Min	Max
A	1.25	1.58
B	2.40	2.83
C	4.06	4.75
D	1.90	2.30
E	4.93	5.28
F	0.76	1.41
G	0.08	0.20
H	0.15	0.31

■ **SUGGESTED PAD LAYOUT**



DO-214AC(SMA)	
Dim	Millimeters
P1	4.00
P2	1.50
P3	6.50
Q1	2.50
Q2	1.70